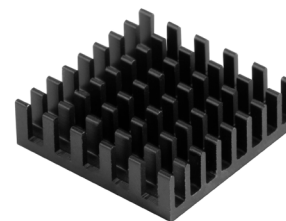




MODEL: HSB08-212106 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



MODEL

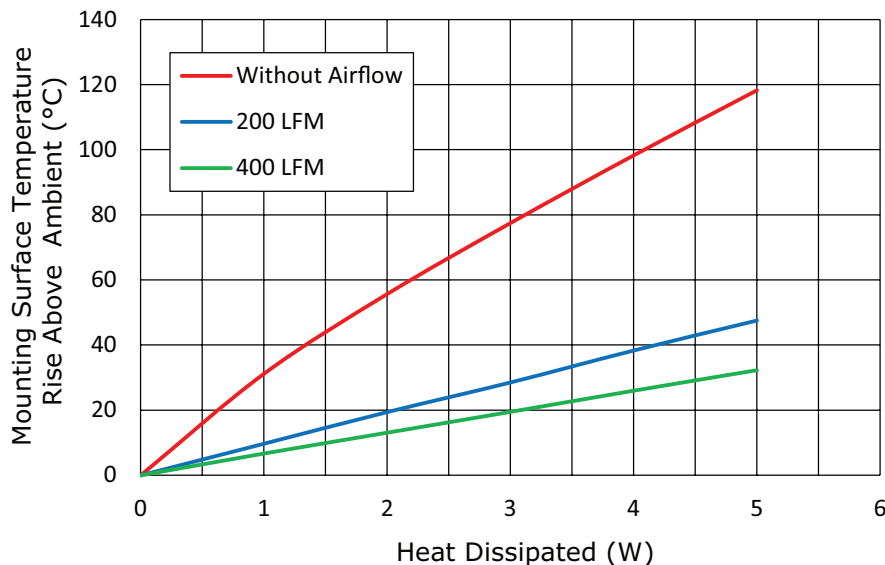
HSB08-212106	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
	25.40	31.2	9.7	6.7	2.95

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	31.2	9.7	6.7
2	55.7	19.4	13.1
3	77.5	28.5	19.5
4	98.3	38.3	26.0
5	118.3	47.5	32.3

T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	3.2 g

